

[ABSTRACT]

A packaging material used for a bag for transporting of a silicon material is a laminate in which a first resin base layer, a barrier layer, a second resin base layer, a resin layer, and a sealant layer are laminated in that order, wherein an indentation elastic modulus (MPa) of the resin layer is smaller than an indentation elastic modulus (MPa) of each of the first resin base layer and the second resin base layer by one or more orders of magnitude, an indentation elastic modulus (MPa) of the sealant layer is smaller than an indentation elastic modulus (MPa) of the first resin base layer and an indentation elastic modulus (MPa) of the second resin base layer by one or more orders of magnitude, and a difference between the indentation elastic modulus (MPa) of the first resin base layer and the indentation elastic modulus (MPa) of the second resin base layer is smaller than a difference between the indentation elastic modulus (MPa) of the second resin base layer and the indentation elastic modulus (MPa) of the resin layer.

FIG. 1